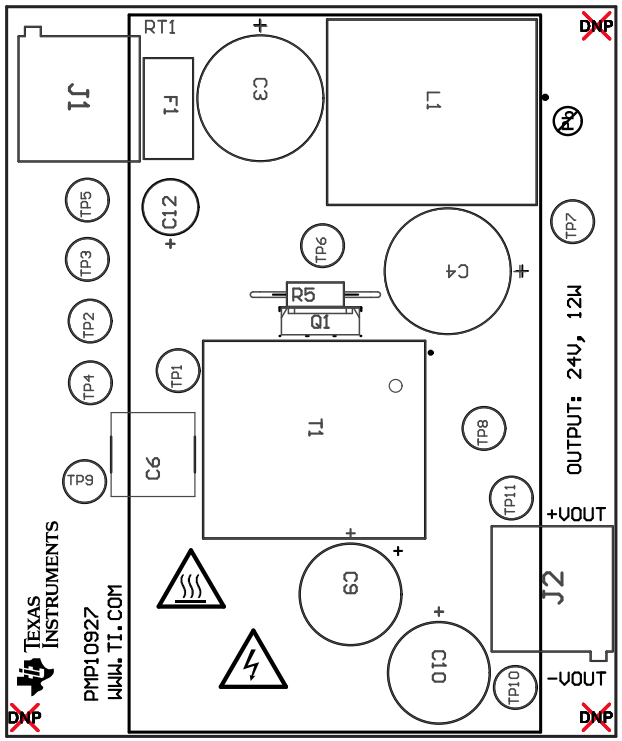
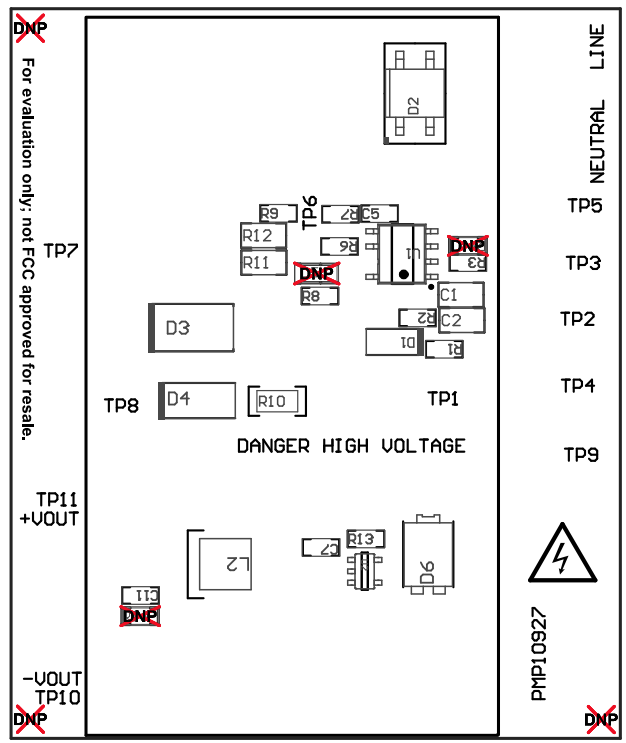
ZZ1 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
ZZ2 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
ZZ3 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP10927	REV: A	SVN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 2/23/2015 11:04:34 AM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP10927	REV: A	SVN REV: Not In VersionControl
	IGNORE ->	Bottom Overlay	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/23/2015 11:04:35 AM		TEXAS INSTRUMENTS

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